Applicants: Ian A. McCabe et al.

JC17 Rec o PC17 3 702 MAY 2005

For : ELECTRO-OPTIC REFLECTIVE ELEMENT ASSEMBLY

Page : 3

Amendments to the Abstract:

Please amend the Abstract on page 62 of the application as follows:

An electro-optic reflective element assembly (510)-includes a pair of substrates (512, 514) and an electro-optic medium (516) sandwiched therebetween. Each of the pair of substrates includes at least one conductive or semi-conductive layer (518, 520) disposed thereon. The electrical connections may electrically connect to a respective layer and may be electrically isolated from the other layer, such as via non-conductive regions (514e) of the substrates and/or deletion lines along one of the conductive layers. The pair of substrates may be positioned relative to one another such that overhang portions (512h, 512i) of the front substrate (512) extend beyond the corresponding edges of the rear substrate (514). The overlapping relationship may provide clearance for electrical connection to the conductive layers of the front and rear substrates such that the electrical connections are substantially not viewable through the front substrate.

A new Abstract sheet is attached.

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PATENT DON01 P-1116

ELECTRO-OPTIC REFLECTIVE ELEMENT ASSEMBLY ABSTRACT OF THE DISCLOSURE

An electro-optic reflective element assembly includes a pair of substrates and an electro-optic medium sandwiched therebetween. Each of the pair of substrates includes at least one conductive or semi-conductive layer disposed thereon. The electrical connections may electrically connect to a respective layer and may be electrically isolated from the other layer, such as via non-conductive regions of the substrates and/or deletion lines along one of the conductive layers. The pair of substrates may be positioned relative to one another such that overhang portions of the front substrate extend beyond the corresponding edges of the rear substrate. The overlapping relationship may provide clearance for electrical connection to the conductive layers of the front and rear substrates such that the electrical connections are substantially not viewable through the front substrate.